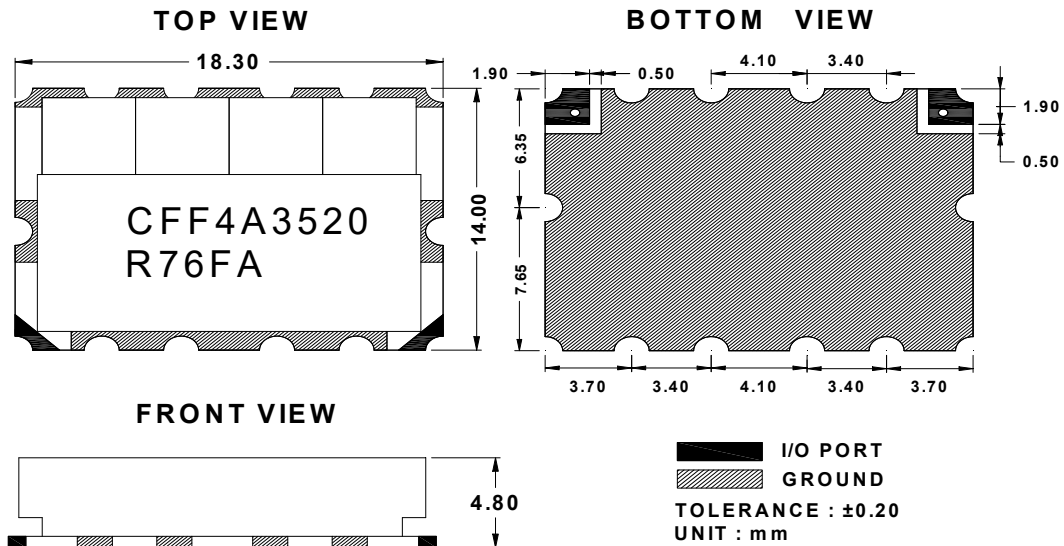


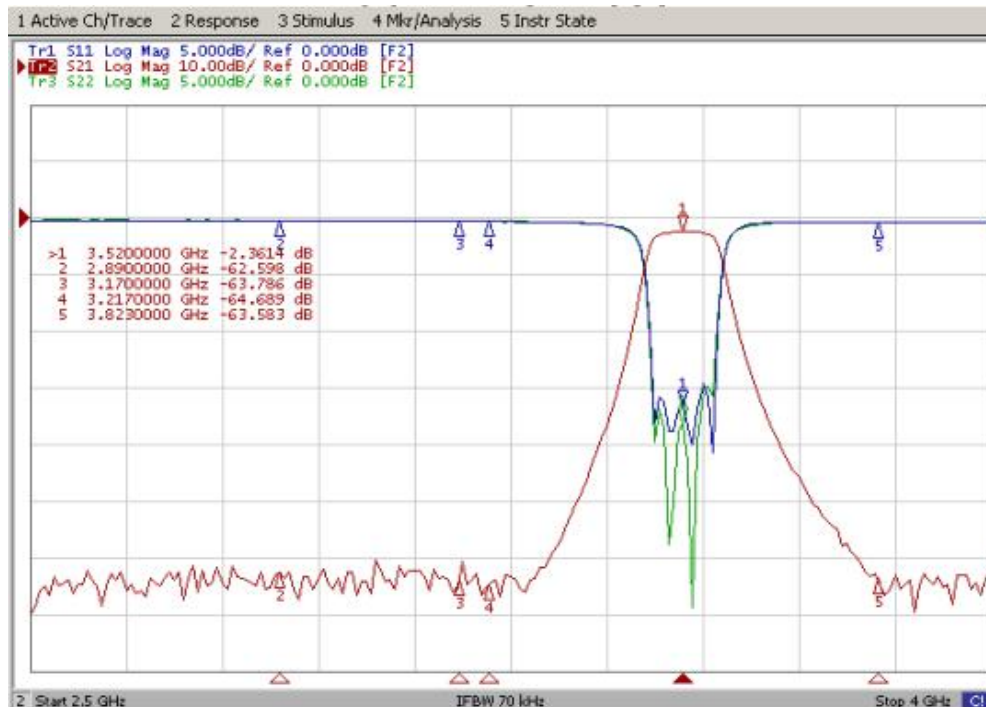
**Electrical Specification**

ITEMS	SPEC	UNIT
Center Frequency [fo]	3520.0	MHz
Bandwidth [BW]	fo ±38.0 [3482~3558]	MHz
Insertion Loss in BW	3.2	dB max
Ripple in BW	1.0	dB max
Return Loss in BW		dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	10.0 dB min. @ fo ± 70.0 [630&3590]	MHz
	60.0 dB min. @ fo ± 303.0 [3217 & 3823]	MHz
	60.0 dB min. @ fo ± [2890& ]	MHz
	35.0dB min. @ fo ± [ 3170& ]	MHz
	50.0dB min. @ fo ± [ 6340& ]	MHz
Group Delay Variation		ns max
Input Power		W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

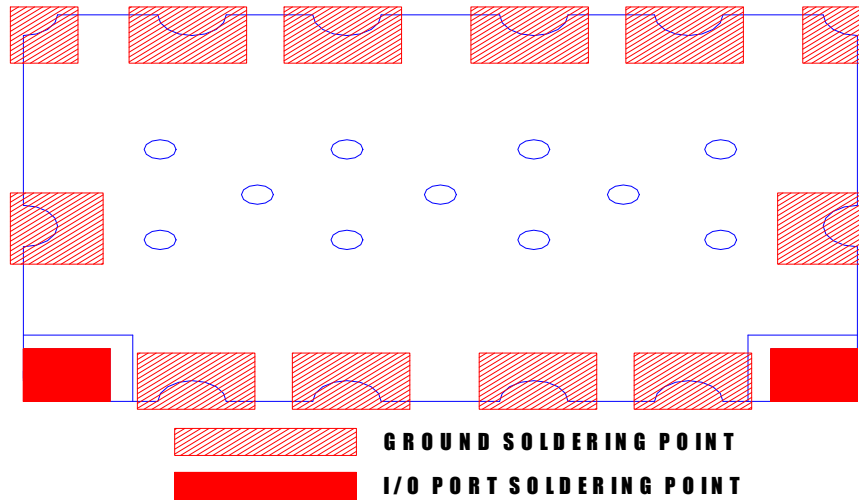
**Mechanical Specification**



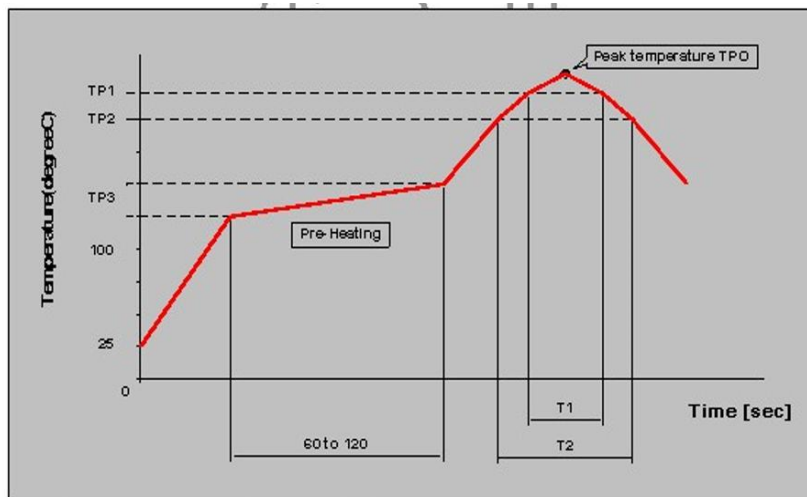
## Plot Data



Recommneded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245 $\pm$ 5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260 $\pm$ 5 $\pm$ 0	240	20	220	70	150 to 180